

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"20040061240".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L2	3584	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:25
L3	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L4	0	L3 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L5	450	L2 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L6	333	L2 and substrate with tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L7	90	L6 and underfill	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L8	184	("4604644"   "4825284"   "4970575"   "4987100"   "5107325"   "5177669"   "5222014"   "5239198"   "5249101"   "5291062"   "5311402").PN. OR ("5450283").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L9	44	L2 and surfactant	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L10	1	"6,576,495".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25

L11	2728	tape with substrate with made	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L12	743	L11 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L13	12	("5918364"   "5939783"   "5985456"   "6013417"   "6044550"   "6165885"   "6281046"   "6316830"   "6319751").PN. OR ("6445075").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L14	2	(US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did.	USPAT	OR	ON	2008/08/18 09:25
L15	149	lead with substrate with bump and 257/778. ccls.	USPAT	OR	ON	2008/08/18 09:25
L16	6	("4624724"   "5538771"   "5614316"   "5670251").PN. OR ("6498400").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L17	24	("2671844"   "3488840"   "4661192"   "4706811"   "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L18	20	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L19	99	lead with substrate with bump and 257/738. ccls.	USPAT	OR	ON	2008/08/18 09:25
L20	99	lead with substrate with bump and 257/738. ccls.	USPAT	OR	ON	2008/08/18 09:25
L21	16	lead with substrate same underfill and 257/738.ccls.	USPAT	OR	ON	2008/08/18 09:25

L22	5	lead with substrate same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:25
L23	8	("5349238"   "5442229"   "5825081"   "6603071"   "6744120").PN. OR ("6867490").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L24	8	lead with bump same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:25
L25	8	lead with bump same underfill same solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:25
L26	13347	lead with bump same solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:25
L27	5602	lead with bump same solder near (resist layer) and 257/738.ccls.	USPAT	OR	ON	2008/08/18 09:25
L28	24	lead with bump same solder near (resist layer) and 257/738.ccls.	USPAT	OR	ON	2008/08/18 09:25
L29	6	("4280132"   "5953814"   "6157085"   "6287895").PN. OR ("6710458").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L30	44	("4604644"   "5084961"   "5089440"   "5121190"   "5194930"   "5274913"   "5400950"   "5542601"   "5578525"   "5615477"   "5704116"   "5710071").PN. OR ("5953814").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L31	1	"5,656,862".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L32	48	lead with substrate with bump and 257/786.ccls.	USPAT	OR	ON	2008/08/18 09:25
L33	18	lead with substrate with bump and 257/782.ccls.	USPAT	OR	ON	2008/08/18 09:25
L34	38	lead with substrate with bump and 257/783.ccls.	USPAT	OR	ON	2008/08/18 09:25

L35	92	L32 L33 L34	USPAT	OR	ON	2008/08/18 09:25
L36	92	L32 L33 L34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L37	2	"20040061240".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L38	3584	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:25
L39	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L40	0	L39 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L41	450	L38 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L42	333	L38 and substrate with tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L43	90	L42 and underfill	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L44	184	("4604644"   "4825284"   "4970575"   "4987100"   "5107325"   "5177669"   "5222014"   "5239198"   "5249101"   "5291062"   "5311402").PN. OR ("5450283").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L45	44	L38 and surfactant	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25

L46	1	"6,576,495".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L47	2728	tape with substrate with made	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L48	743	L47 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L49	12	("5918364"   "5939783"   "5985456"   "6013417"   "6044550"   "6165885"   "6281046"   "6316830"   "6319751").PN. OR ("6445075").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L50	2	(US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did.	USPAT	OR	ON	2008/08/18 09:25
L51	149	lead with substrate with bump and 257/778. ccls.	USPAT	OR	ON	2008/08/18 09:25
L52	6	("4624724"   "5538771"   "5614316"   "5670251").PN. OR ("6498400").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L53	24	("2671844"   "3488840"   "4661192"   "4706811"   "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L54	20	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L55	99	lead with substrate with bump and 257/738. ccls.	USPAT	OR	ON	2008/08/18 09:25
L56	99	lead with substrate with bump and 257/738. ccls.	USPAT	OR	ON	2008/08/18 09:25

L57	4040	(257/e23.021).CCL.S.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:25
L58	2	L57 and solder with resist same wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L59	0	L57 and solder near2 (resist mask) with underfill with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L60	0	(257/e23.\$4).ccls. and solder near2 (resist mask) with underfill with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L61	165	(257/e23.\$4).ccls. and solder near2 (resist mask) with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L62	156	(257/e23.\$4).ccls. and solder near2 (resist mask) and pad with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L63	59	(257/e23.\$4).ccls. and solder near2 (resist mask) same pad with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L64	19	("4786545"   "5055321"   "5278429"   "5473512"   "5519251"   "5756380"   "5816478"   "5834832"   "5872399"   "5925403"   "6197615"   "6286207"   "6288451"   "6323542"   "6344753").PN. OR ("6806560").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L65	77758	(257/e23.\$4).ccls. antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25

L66	0	(257/e23.\$4).cds. and antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L67	0	(257/e23.\$4).cds. and antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L68	0	(257/e23.\$4).cds. and nonrepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L69	23	(257/e23.\$4).cds. and \$5repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L70	1	(257/e23.\$4).cds. and anti near2 repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L71	1	("257"/\$6).cds. and anti near2 repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L72	0	("257"/\$6).cds. and solder near2 (resist mask) with underfill with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L73	0	("257"/\$6).cds. and solder near2 (resist mask) with underfill\$3 with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L74	2	("257"/\$6).cds. and solder near2 (resist mask) with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L75	29	("257"/\$6).cds. and solder near2 (resist mask) with (improv\$3, increas\$3) with attach \$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25

L76	4	("5703402"   "5801440"   "6329228").PN. OR ("6608388").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L77	20	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L78	24	("2671844"   "3488840"   "4661192"   "4706811"   "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L79	2	"3488840".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L80	12	("4604644"   "5084961"   "5089440"   "5121190"   "5194930"   "5274913"   "5400950"   "5542601"   "5578525"   "5615477"   "5704116"   "5710071").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L81	129	("5710071").URPN.	USPAT	OR	ON	2008/08/18 09:25
L82	5	"5,71,071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L83	2	"5710071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L84	2	"5,710,071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25



L85	11	("4604644"   "5144747"   "5182632"   "5203076"   "5218234"   "5296738"   "5311059"   "5385869"   "5473512"   "5488200"   "5594626").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L86	115	("4138691"   "4268848"   "4280132"   "4843036"   "5001542"   "5107325").PN. OR ("5218234").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L87	3455	257/778.cds.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L88	686	L87 and solder near2 (resist mask )	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L89	374	L88 and polyimide	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L90	260	L88 and polyimide	USPAT	OR	ON	2008/08/18 09:25
L91	29	("4658332"   "4740414"   "4847136"   "4847146"   "4855872"   "4873615"   "5026624"   "5110867"   "5258648"   "5262280"   "5278010"   "5304457"   "5329423"   "5391435"   "5439766"   "5439779"   "5473119"   "5493075"   "5496769"   "5511306"   "5535101"   "5579573"   "5633535"   "5801446"   "5808874"   "5821305"   "5866952"   "6002590"   "6054250").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L92	158	("4604644"   "4864470"   "4931345"   "5107325"   "5172303"   "5241133"   "5378869").PN. OR ("5535101").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25

L93	1876934	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L94	113324	L93 and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L95	67123	L93 and "438"/\$.ccls.	USPAT	OR	ON	2008/08/18 09:25
L96	37101	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L97	2357	L96 and "438"/\$.ccls.	USPAT	OR	ON	2008/08/18 09:25
L98	21999	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers	USPAT	OR	ON	2008/08/18 09:25
L99	354333	L98 and solder ball	USPAT	OR	ON	2008/08/18 09:25
L100	316	L98 and solder near2 ball	USPAT	OR	ON	2008/08/18 09:25
L101	14	polyimide near2 substrate with thickness with micrometers	USPAT	OR	ON	2008/08/18 09:25
L102	41	polyimide near5 substrate with thickness with micrometers	USPAT	OR	ON	2008/08/18 09:25
L103	27	L102 not L101	USPAT	OR	ON	2008/08/18 09:25
L104	7	("3948429"   "4255644"   "4300715"   "4371912"   "4607779"   "4638937"   "4638938").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L105	39	("3948429"   "4255644"   "4300715"   "4371912"   "4607779"   "4638937"   "4638938").PN. OR ("5201451").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25

L106	1062	thin with polyimide with substrate and "257"/\$. ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L107	659	thin with polyimide with substrate and "257"/\$. ccls.	USPAT	OR	ON	2008/08/18 09:25
L108	54	thin with polyimide with substrate with "mu.m" and "257"/\$.ccls.	USPAT	OR	ON	2008/08/18 09:25
L109	236	(IC integrated near1 circuit chip die semiconductor silicon wafer) and thin with polyimide with substrate with "mu.m"	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L110	134	L109 not "44"	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L111	184	L109 not L108	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L112	79	L109 not L108	USPAT; USOCR	OR	ON	2008/08/18 09:25
L113	419	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m"	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L114	239	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m"	USPAT	OR	ON	2008/08/18 09:25
L115	0	jp-361633-\$.did.	USPAT	OR	ON	2008/08/18 09:25
L116	0	jp-361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L117	1	jp-1361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L118	0	jp-11361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25

L119	2	JP-2001176918-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L120	20	("20010002066"   "20010040290"   "20010054751"   "4263606"   "4676864"   "4786545"   "4963974"   "5049718"   "5060052"   "5132772"   "5139610"   "5384204"   "5844304"   "5910685"   "6028011"   "6175151"   "6262488"   "6297142").PN. OR ("6518649").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L121	18	("20010002066"   "20010040290"   "20010054751"   "4263606"   "4676864"   "4786545"   "4963974"   "5049718"   "5060052"   "5132772"   "5139610"   "5384204"   "5844304"   "5910685"   "6028011"   "6175151"   "6262488"   "6297142").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L122	1	("6592783").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L123	17	("4551912"   "4811081"   "4851964"   "4977441"   "5032542"   "5075252"   "5153707"   "5232532"   "5427641"   "5726491"   "5949134"   "6100112"   "6274405"   "6313526"   "6315156"   "6388888"   "6559524").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L124	7	("5260168"   "5378581"   "5825081"   "6313526"   "6320135"   "6388888"   "6433414").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25

L125	18	("20010002066"   "20010040290"   "20010054751"   "4263606"   "4676864"   "4786545"   "4963974"   "5049718"   "5060052"   "5132772"   "5139610"   "5384204"   "5844304"   "5910685"   "6028011"   "6175151"   "6262488"   "6297142").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L126	2	jp-2001176918-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L127	2	"20020043713".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L128	1073	(257/797).CQLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:25
L129	7	L128 and dummy near2 pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L130	15	L128 and mark with probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L131	2	"20040061240".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L132	3584	(257/778).CQLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:25
L133	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25

L134	0	L133 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L135	450	L132 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L136	333	L132 and substrate with tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L137	90	L136 and underfill	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L138	184	("4604644"   "4825284"   "4970575"   "4987100"   "5107325"   "5177669"   "5222014"   "5239198"   "5249101"   "5291062"   "5311402").PN. OR ("5450283").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L139	44	L132 and surfactant	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L140	1	"6,576,495".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L141	2728	tape with substrate with made	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L142	743	L141 and "257"/\$.cds.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L143	12	("5918364"   "5939783"   "5985456"   "6013417"   "6044550"   "6165885"   "6281046"   "6316830"   "6319751").PN. OR ("6445075").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L144	2	(US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did.	USPAT	OR	ON	2008/08/18 09:25
L145	149	lead with substrate with bump and 257/778. cds.	USPAT	OR	ON	2008/08/18 09:25

L146	6	("4624724"   "5538771"   "5614316"   "5670251").PN. OR ("6498400").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L147	24	("2671844"   "3488840"   "4661192"   "4706811"   "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L148	20	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L149	99	lead with substrate with bump and 257/738. cds.	USPAT	OR	ON	2008/08/18 09:25
L150	99	lead with substrate with bump and 257/738. cds.	USPAT	OR	ON	2008/08/18 09:25
L151	16	lead with substrate same underfill and 257/738.cds.	USPAT	OR	ON	2008/08/18 09:25
L152	5	lead with substrate same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:25
L153	8	("5349238"   "5442229"   "5825081"   "6603071"   "6744120").PN. OR ("6867490").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L154	8	lead with bump same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:25
L155	8	lead with bump same underfill same solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:25
L156	13347	lead with bump ssame solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:25
L157	5602	lead with bump ssame solder near (resist layer) and 257/738.cds.	USPAT	OR	ON	2008/08/18 09:25

L158	24	lead with bump same solder near (resist layer) and 257/738.ccls.	USPAT	OR	ON	2008/08/18 09:25
L159	6	("4280132"   "5953814"   "6157085"   "6287895").PN. OR ("6710458").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L160	44	("4604644"   "5084961"   "5089440"   "5121190"   "5194930"   "5274913"   "5400950"   "5542601"   "5578525"   "5615477"   "5704116"   "5710071").PN. OR ("5953814").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L161	1	"5,656,862".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L162	48	lead with substrate with bump and 257/786.ccls.	USPAT	OR	ON	2008/08/18 09:25
L163	18	lead with substrate with bump and 257/782.ccls.	USPAT	OR	ON	2008/08/18 09:25
L164	38	lead with substrate with bump and 257/783.ccls.	USPAT	OR	ON	2008/08/18 09:25
L165	92	L162 L163 L164	USPAT	OR	ON	2008/08/18 09:25
L166	92	L162 L163 L164	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L167	2	"20040061240".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L168	3584	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:25
L169	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25



L170	0	L169 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L171	450	L168 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L172	333	L168 and substrate with tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L173	90	L172 and underfill	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L174	184	("4604644"   "4825284"   "4970575"   "4987100"   "5107325"   "5177669"   "5222014"   "5239198"   "5249101"   "5291062"   "5311402").PN. OR ("5450283").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L175	44	L168 and surfactant	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L176	1	"6,576,495".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L177	2728	tape with substrate with made	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L178	743	L177 and "257"/\$.cds.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L179	12	("5918364"   "5939783"   "5985456"   "6013417"   "6044550"   "6165885"   "6281046"   "6316830"   "6319751").PN. OR ("6445075").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L180	2	(US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did.	USPAT	OR	ON	2008/08/18 09:25
L181	149	lead with substrate with bump and 257/778. cds.	USPAT	OR	ON	2008/08/18 09:25

L182	6	("4624724"   "5538771"   "5614316"   "5670251").PN. OR ("6498400").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L183	24	("2671844"   "3488840"   "4661192"   "4706811" "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L184	20	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L185	99	lead with substrate with bump and 257/738. ccls.	USPAT	OR	ON	2008/08/18 09:25
L186	99	lead with substrate with bump and 257/738. ccls.	USPAT	OR	ON	2008/08/18 09:25
L187	4040	(257/e23.021).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:25
L188	2	L187 and solder with resist same wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L189	0	L187 and solder near2 (resist mask) with underfill with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L190	0	(257/e23.\$4).ccls. and solder near2 (resist mask) with underfill with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L191	165	(257/e23.\$4).ccls. and solder near2 (resist mask) with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25

L192	156	(257/e23.\$4).cds. and solder near2 (resist mask) and pad with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L193	59	(257/e23.\$4).cds. and solder near2 (resist mask) same pad with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L194	19	("4786545"   "5055321"   "5278429"   "5473512"   "5519251"   "5756380"   "5816478"   "5834832"   "5872399"   "5925403"   "6197615"   "6286207"   "6288451"   "6323542"   "6344753").PN. OR ("6806560").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L195	77758	(257/e23.\$4).cds. antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L196	0	(257/e23.\$4).cds. and antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L197	0	(257/e23.\$4).cds. and antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L198	0	(257/e23.\$4).cds. and nonrepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L199	23	(257/e23.\$4).cds. and \$5repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L200	1	(257/e23.\$4).cds. and anti near2 repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25

L201	1	("257"/\$6).cds. and anti near2 repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L202	0	("257"/\$6).cds. and solder near2 (resist mask) with underfill with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L203	0	("257"/\$6).cds. and solder near2 (resist mask) with underfill\$3 with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L204	2	("257"/\$6).cds. and solder near2 (resist mask) with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L205	29	("257"/\$6).cds. and solder near2 (resist mask) with (improv\$3, increas\$3) with attach \$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L206	4	("5703402"   "5801440"   "6329228").PN. OR ("6608388").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L207	20	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L208	24	("2671844"   "3488840"   "4661192"   "4706811"   "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L209	2	"3488840".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25

L210	12	("4604644"   "5084961"   "5089440"   "5121190"   "5194930"   "5274913"   "5400950"   "5542601"   "5578525"   "5615477"   "5704116"   "5710071").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L211	129	("5710071").URPN.	USPAT	OR	ON	2008/08/18 09:25
L212	5	"5,71,071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L213	2	"5710071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L214	2	"5,710,071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L215	11	("4604644"   "5144747"   "5182632"   "5203076"   "5218234"   "5296738"   "5311059"   "5385869"   "5473512"   "5488200"   "5594626").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L216	115	("4138691"   "4268848"   "4280132"   "4843036"   "5001542"   "5107325").PN. OR ("5218234").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L217	3455	257/778.cds.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L218	686	L217 and solder near2 (resist mask )	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L219	374	L218 and polyimide	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L220	260	L218 and polyimide	USPAT	OR	ON	2008/08/18 09:25

L221	29	("4658332"   "4740414"   "4847136"   "4847146"   "4855872"   "4873615"   "5026624"   "5110867"   "5258648"   "5262280"   "5278010"   "5304457"   "5329423"   "5391435"   "5439766"   "5439779"   "5473119"   "5493075"   "5496769"   "5511306"   "5535101"   "5579573"   "5633535"   "5801446"   "5808874"   "5821305"   "5866952"   "6002590"   "6054250").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L222	158	("4604644"   "4864470"   "4931345"   "5107325"   "5172303"   "5241133"   "5378869").PN. OR ("5535101").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L223	1876934	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L224	113324	L223 and "438"/\$.cds.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L225	67123	L223 and "438"/\$.cds.	USPAT	OR	ON	2008/08/18 09:25
L226	37101	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L227	2357	L226 and "438"/\$.cds.	USPAT	OR	ON	2008/08/18 09:25
L228	21999	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers	USPAT	OR	ON	2008/08/18 09:25

L229	354333	L228 and solder ball	USPAT	OR	ON	2008/08/18 09:25
L230	316	L228 and solder near2 ball	USPAT	OR	ON	2008/08/18 09:25
L231	14	polyimide near2 substrate with thickness with micrometers	USPAT	OR	ON	2008/08/18 09:25
L232	41	polyimide near5 substrate with thickness with micrometers	USPAT	OR	ON	2008/08/18 09:25
L233	27	L232 not L231	USPAT	OR	ON	2008/08/18 09:25
L234	7	("3948429"   "4255644"   "4300715"   "4371912"   "4607779"   "4638937"   "4638938").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L235	39	("3948429"   "4255644"   "4300715"   "4371912"   "4607779"   "4638937"   "4638938").PN. OR ("5201451").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L236	1062	thin with polyimide with substrate and "257"/\$. ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L237	659	thin with polyimide with substrate and "257"/\$. ccls.	USPAT	OR	ON	2008/08/18 09:25
L238	54	thin with polyimide with substrate with "mu.m" and "257"/\$.ccls.	USPAT	OR	ON	2008/08/18 09:25
L239	236	(IC integrated near1 circuit chip die semiconductor silicon wafer) and thin with polyimide with substrate with "mu.m"	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L240	134	L239 not "44"	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L241	184	L239 not L238	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L242	79	L239 not L238	USPAT; USOCR	OR	ON	2008/08/18 09:25
L243	419	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m"	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25

L244	239	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m"	USPAT	OR	ON	2008/08/18 09:25
L245	0	jp-361633-\$.did.	USPAT	OR	ON	2008/08/18 09:25
L246	0	jp-361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L247	1	jp-1361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L248	0	jp-11361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L249	2	JP-2001176918-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L250	20	("20010002066"   "20010040290"   "20010054751"   "4263606"   "4676864"   "4786545"   "4963974"   "5049718"   "5060052"   "5132772"   "5139610"   "5384204"   "5844304"   "5910685"   "6028011"   "6175151"   "6262488"   "6297142").PN. OR ("6518649").JRP.N.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L251	18	("20010002066"   "20010040290"   "20010054751"   "4263606"   "4676864"   "4786545"   "4963974"   "5049718"   "5060052"   "5132772"   "5139610"   "5384204"   "5844304"   "5910685"   "6028011"   "6175151"   "6262488"   "6297142").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25



L252	1	("6592783").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L253	17	("4551912"   "4811081"   "4851964"   "4977441"   "5032542"   "5075252"   "5153707"   "5232532"   "5427641"   "5726491"   "5949134"   "6100112"   "6274405"   "6313526"   "6315156"   "6388888"   "6559524").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L254	7	("5260168"   "5378581"   "5825081"   "6313526"   "6320135"   "6388888"   "6433414").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L255	18	("20010002066"   "20010040290"   "20010054751"   "4263606"   "4676864"   "4786545"   "4963974"   "5049718"   "5060052"   "5132772"   "5139610"   "5384204"   "5844304"   "5910685"   "6028011"   "6175151"   "6262488"   "6297142").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:25
L256	2	jp-2001176918-\$.dld.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L257	2	"20020043713".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25
L258	1073	(257/797).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:25
L259	7	L258 and dummy near2 pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:25

L260	15	L258 and mark with probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L261	976	bump with solder with free	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L262	976	bump with solder with free	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L263	2	"20040061240".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L264	3584	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:26
L265	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L266	0	L265 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L267	450	L264 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L268	333	L264 and substrate with tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L269	90	L268 and underfill	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L270	184	("4604644"   "4825284"   "4970575"   "4987100"   "5107325"   "5177669"   "5222014"   "5239198"   "5249101"   "5291062"   "5311402").PN. OR ("5450283").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26

L271	44	L264 and surfactant	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L272	1	"6,576,495".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L273	2728	tape with substrate with made	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L274	743	L273 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L275	12	("5918364"   "5939783"   "5985456"   "6013417"   "6044550"   "6165885"   "6281046"   "6316830"   "6319751").PN. OR ("6445075").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L276	2	(US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did.	USPAT	OR	ON	2008/08/18 09:26
L277	149	lead with substrate with bump and 257/778. ccls.	USPAT	OR	ON	2008/08/18 09:26
L278	6	("4624724"   "5538771"   "5614316"   "5670251").PN. OR ("6498400").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L279	24	("2671844"   "3488840"   "4661192"   "4706811"   "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L280	20	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L281	99	lead with substrate with bump and 257/738. ccls.	USPAT	OR	ON	2008/08/18 09:26
L282	99	lead with substrate with bump and 257/738. ccls.	USPAT	OR	ON	2008/08/18 09:26

L283	16	lead with substrate same underfill and 257/738.ccls.	USPAT	OR	ON	2008/08/18 09:26
L284	5	lead with substrate same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:26
L285	8	("5349238"   "5442229"   "5825081"   "6603071"   "6744120").PN. OR ("6867490").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L286	8	lead with bump same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:26
L287	8	lead with bump same underfill same solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:26
L288	13347	lead with bump same solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:26
L289	5602	lead with bump same solder near (resist layer) and 257/738.ccls.	USPAT	OR	ON	2008/08/18 09:26
L290	24	lead with bump same solder near (resist layer) and 257/738.ccls.	USPAT	OR	ON	2008/08/18 09:26
L291	6	("4280132"   "5953814"   "6157085"   "6287895").PN. OR ("6710458").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L292	44	("4604644"   "5084961"   "5089440"   "5121190"   "5194930"   "5274913"   "5400950"   "5542601"   "5578525"   "5615477"   "5704116"   "5710071").PN. OR ("5953814").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L293	1	"5,656,862".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L294	48	lead with substrate with bump and 257/786.ccls.	USPAT	OR	ON	2008/08/18 09:26
L295	18	lead with substrate with bump and 257/782.ccls.	USPAT	OR	ON	2008/08/18 09:26

L296	38	lead with substrate with bump and 257/783. ccls.	USPAT	OR	ON	2008/08/18 09:26
L297	92	L294 L295 L296	USPAT	OR	ON	2008/08/18 09:26
L298	92	L294 L295 L296	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L299	2	"20040061240".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L300	3584	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:26
L301	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L302	0	L301 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L303	450	L300 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L304	333	L300 and substrate with tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L305	90	L304 and underfill	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L306	184	("4604644"   "4825284"   "4970575"   "4987100"   "5107325"   "5177669"   "5222014"   "5239198"   "5249101"   "5291062"   "5311402").PN. OR ("5450283").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26

L307	44	L300 and surfactant	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L308	1	"6,576,495".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L309	2728	tape with substrate with made	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L310	743	L309 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L311	12	("5918364"   "5939783"   "5985456"   "6013417"   "6044550"   "6165885"   "6281046"   "6316830"   "6319751").PN. OR ("6445075").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L312	2	(US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did.	USPAT	OR	ON	2008/08/18 09:26
L313	149	lead with substrate with bump and 257/778. ccls.	USPAT	OR	ON	2008/08/18 09:26
L314	6	("4624724"   "5538771"   "5614316"   "5670251").PN. OR ("6498400").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L315	24	("2671844"   "3488840"   "4661192"   "4706811"   "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L316	20	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L317	99	lead with substrate with bump and 257/738. ccls.	USPAT	OR	ON	2008/08/18 09:26
L318	99	lead with substrate with bump and 257/738. ccls.	USPAT	OR	ON	2008/08/18 09:26

L319	4040	(257/e23.021).CQLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:26
L320	2	L319 and solder with resist same wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L321	0	L319 and solder near2 (resist mask) with underfill with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L322	0	(257/e23.\$4).cds. and solder near2 (resist mask) with underfill with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L323	165	(257/e23.\$4).cds. and solder near2 (resist mask) with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L324	156	(257/e23.\$4).cds. and solder near2 (resist mask) and pad with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L325	59	(257/e23.\$4).cds. and solder near2 (resist mask) same pad with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L326	19	("4786545"   "5055321"   "5278429"   "5473512"   "5519251"   "5756380"   "5816478"   "5834832"   "5872399"   "5925403"   "6197615"   "6286207"   "6288451"   "6323542"   "6344753").PN. OR ("6806560").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L327	77758	(257/e23.\$4).cds. antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26

L328	0	(257/e23.\$4).cds. and antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L329	0	(257/e23.\$4).cds. and antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L330	0	(257/e23.\$4).cds. and nonrepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L331	23	(257/e23.\$4).cds. and \$5repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L332	1	(257/e23.\$4).cds. and anti near2 repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L333	1	("257"/\$6).cds. and anti near2 repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L334	0	("257"/\$6).cds. and solder near2 (resist mask) with underfill with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L335	0	("257"/\$6).cds. and solder near2 (resist mask) with underfill\$3 with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L336	2	("257"/\$6).cds. and solder near2 (resist mask) with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L337	29	("257"/\$6).cds. and solder near2 (resist mask) with (improv\$3, increas\$3) with attach \$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26



L338	4	("5703402"   "5801440"   "6329228").PN. OR ("6608388").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L339	20	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L340	24	("2671844"   "3488840"   "4661192"   "4706811"   "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L341	2	"3488840".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L342	12	("4604644"   "5084961"   "5089440"   "5121190"   "5194930"   "5274913"   "5400950"   "5542601"   "5578525"   "5615477"   "5704116"   "5710071").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L343	129	("5710071").URPN.	USPAT	OR	ON	2008/08/18 09:26
L344	5	"5,71,071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L345	2	"5710071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L346	2	"5,710,071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26

L347	11	("4604644"   "5144747"   "5182632"   "5203076"   "5218234"   "5296738"   "5311059"   "5385869"   "5473512"   "5488200"   "5594626").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L348	115	("4138691"   "4268848"   "4280132"   "4843036"   "5001542"   "5107325").PN. OR ("5218234").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L349	3455	257/778.cds.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L350	686	L349 and solder near2 (resist mask )	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L351	374	L350 and polyimide	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L352	260	L350 and polyimide	USPAT	OR	ON	2008/08/18 09:26
L353	29	("4658332"   "4740414"   "4847136"   "4847146"   "4855872"   "4873615"   "5026624"   "5110867"   "5258648"   "5262280"   "5278010"   "5304457"   "5329423"   "5391435"   "5439766"   "5439779"   "5473119"   "5493075"   "5496769"   "5511306"   "5535101"   "5579573"   "5633535"   "5801446"   "5808874"   "5821305"   "5866952"   "6002590"   "6054250").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L354	158	("4604644"   "4864470"   "4931345"   "5107325"   "5172303"   "5241133"   "5378869").PN. OR ("5535101").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26

L355	1876934	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L356	113324	L355 and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L357	67123	L355 and "438"/\$.ccls.	USPAT	OR	ON	2008/08/18 09:26
L358	37101	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L359	2357	L358 and "438"/\$.ccls.	USPAT	OR	ON	2008/08/18 09:26
L360	21999	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers	USPAT	OR	ON	2008/08/18 09:26
L361	354333	L360 and solder ball	USPAT	OR	ON	2008/08/18 09:26
L362	316	L360 and solder near2 ball	USPAT	OR	ON	2008/08/18 09:26
L363	14	polyimide near2 substrate with thickness with micrometers	USPAT	OR	ON	2008/08/18 09:26
L364	41	polyimide near5 substrate with thickness with micrometers	USPAT	OR	ON	2008/08/18 09:26
L365	27	L364 not L363	USPAT	OR	ON	2008/08/18 09:26
L366	7	("3948429"   "4255644"   "4300715"   "4371912"   "4607779"   "4638937"   "4638938").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L367	39	("3948429"   "4255644"   "4300715"   "4371912"   "4607779"   "4638937"   "4638938").PN. OR ("5201451").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26

L368	1062	thin with polyimide with substrate and "257"/\$.cls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L369	659	thin with polyimide with substrate and "257"/\$.cls.	USPAT	OR	ON	2008/08/18 09:26
L370	54	thin with polyimide with substrate with "mu.m" and "257"/\$.cls.	USPAT	OR	ON	2008/08/18 09:26
L371	236	(IC integrated near1 circuit chip die semiconductor silicon wafer) and thin with polyimide with substrate with "mu.m"	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L372	134	L371 not "44"	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L373	184	L371 not L370	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L374	79	L371 not L370	USPAT; USOCR	OR	ON	2008/08/18 09:26
L375	419	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m"	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L376	239	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m"	USPAT	OR	ON	2008/08/18 09:26
L377	0	jp-361633-\$.did.	USPAT	OR	ON	2008/08/18 09:26
L378	0	jp-361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L379	1	jp-1361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L380	0	jp-11361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26

L381	2	JP-2001176918-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L382	20	("20010002066"   "20010040290"   "20010054751"   "4263606"   "4676864"   "4786545"   "4963974"   "5049718"   "5060052"   "5132772"   "5139610"   "5384204"   "5844304"   "5910685"   "6028011"   "6175151"   "6262488"   "6297142").PN. OR ("6518649").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L383	18	("20010002066"   "20010040290"   "20010054751"   "4263606"   "4676864"   "4786545"   "4963974"   "5049718"   "5060052"   "5132772"   "5139610"   "5384204"   "5844304"   "5910685"   "6028011"   "6175151"   "6262488"   "6297142").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L384	1	("6592783").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L385	17	("4551912"   "4811081"   "4851964"   "4977441"   "5032542"   "5075252"   "5153707"   "5232532"   "5427641"   "5726491"   "5949134"   "6100112"   "6274405"   "6313526"   "6315156"   "6388888"   "6559524").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L386	7	("5260168"   "5378581"   "5825081"   "6313526"   "6320135"   "6388888"   "6433414").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26

L387	18	("20010002066"   "20010040290"   "20010054751"   "4263606"   "4676864"   "4786545" "4963974"   "5049718"   "5060052" "5132772"   "5139610"   "5384204" "5844304"   "5910685"   "6028011" "6175151"   "6262488"   "6297142").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L388	2	jp-2001176918-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L389	2	"20020043713".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L390	1073	(257/797).CQLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:26
L391	7	L390 and dummy near2 pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L392	15	L390 and mark with probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L393	2	"20040061240".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L394	3584	(257/778).CQLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:26
L395	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26

L396	0	L395 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L397	450	L394 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L398	333	L394 and substrate with tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L399	90	L398 and underfill	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L400	184	("4604644"   "4825284"   "4970575"   "4987100"   "5107325"   "5177669"   "5222014"   "5239198"   "5249101"   "5291062"   "5311402").PN. OR ("5450283").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L401	44	L394 and surfactant	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L402	1	"6,576,495".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L403	2728	tape with substrate with made	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L404	743	L403 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L405	12	("5918364"   "5939783"   "5985456"   "6013417"   "6044550"   "6165885"   "6281046"   "6316830"   "6319751").PN. OR ("6445075").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L406	2	(US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did.	USPAT	OR	ON	2008/08/18 09:26
L407	149	lead with substrate with bump and 257/778. ccls.	USPAT	OR	ON	2008/08/18 09:26

L408	6	("4624724"   "5538771"   "5614316"   "5670251").PN. OR ("6498400").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L409	24	("2671844"   "3488840"   "4661192"   "4706811"   "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L410	20	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L411	99	lead with substrate with bump and 257/738. ccls.	USPAT	OR	ON	2008/08/18 09:26
L412	99	lead with substrate with bump and 257/738. ccls.	USPAT	OR	ON	2008/08/18 09:26
L413	16	lead with substrate same underfill and 257/738.ccls.	USPAT	OR	ON	2008/08/18 09:26
L414	5	lead with substrate same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:26
L415	8	("5349238"   "5442229"   "5825081"   "6603071"   "6744120").PN. OR ("6867490").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L416	8	lead with bump same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:26
L417	8	lead with bump same underfill same solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:26
L418	13347	lead with bump ssame solder near (resist layer)	USPAT	OR	ON	2008/08/18 09:26
L419	5602	lead with bump ssame solder near (resist layer) and 257/738.ccls.	USPAT	OR	ON	2008/08/18 09:26



L420	24	lead with bump same solder near (resist layer) and 257/738.ccls.	USPAT	OR	ON	2008/08/18 09:26
L421	6	("4280132"   "5953814"   "6157085"   "6287895").PN. OR ("6710458").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L422	44	("4604644"   "5084961"   "5089440"   "5121190"   "5194930"   "5274913"   "5400950"   "5542601"   "5578525"   "5615477"   "5704116"   "5710071").PN. OR ("5953814").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L423	1	"5,656,862".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L424	48	lead with substrate with bump and 257/786.ccls.	USPAT	OR	ON	2008/08/18 09:26
L425	18	lead with substrate with bump and 257/782.ccls.	USPAT	OR	ON	2008/08/18 09:26
L426	38	lead with substrate with bump and 257/783.ccls.	USPAT	OR	ON	2008/08/18 09:26
L427	92	L424 L425 L426	USPAT	OR	ON	2008/08/18 09:26
L428	92	L424 L425 L426	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L429	2	"20040061240".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L430	3584	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:26
L431	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26

L432	0	L431 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L433	450	L430 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L434	333	L430 and substrate with tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L435	90	L434 and underfill	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L436	184	("4604644"   "4825284"   "4970575"   "4987100"   "5107325"   "5177669"   "5222014"   "5239198"   "5249101"   "5291062"   "5311402").PN. OR ("5450283").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L437	44	L430 and surfactant	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L438	1	"6,576,495".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L439	2728	tape with substrate with made	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L440	743	L439 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L441	12	("5918364"   "5939783"   "5985456"   "6013417"   "6044550"   "6165885"   "6281046"   "6316830"   "6319751").PN. OR ("6445075").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L442	2	(US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did.	USPAT	OR	ON	2008/08/18 09:26
L443	149	lead with substrate with bump and 257/778. ccls.	USPAT	OR	ON	2008/08/18 09:26

L444	6	("4624724"   "5538771"   "5614316"   "5670251").PN. OR ("6498400").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L445	24	("2671844"   "3488840"   "4661192"   "4706811"   "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L446	20	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L447	99	lead with substrate with bump and 257/738. ccls.	USPAT	OR	ON	2008/08/18 09:26
L448	99	lead with substrate with bump and 257/738. ccls.	USPAT	OR	ON	2008/08/18 09:26
L449	4040	(257/e23.021).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:26
L450	2	L449 and solder with resist same wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L451	0	L449 and solder near2 (resist mask) with underfill with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L452	0	(257/e23.\$4).ccls. and solder near2 (resist mask) with underfill with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L453	165	(257/e23.\$4).ccls. and solder near2 (resist mask) with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26

L454	156	(257/e23.\$4).cds. and solder near2 (resist mask) and pad with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L455	59	(257/e23.\$4).cds. and solder near2 (resist mask) same pad with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L456	19	("4786545"   "5055321"   "5278429"   "5473512"   "5519251"   "5756380"   "5816478"   "5834832"   "5872399"   "5925403"   "6197615"   "6286207"   "6288451"   "6323542"   "6344753").PN. OR ("6806560").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L457	77758	(257/e23.\$4).cds. antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L458	0	(257/e23.\$4).cds. and antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L459	0	(257/e23.\$4).cds. and antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L460	0	(257/e23.\$4).cds. and nonrepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L461	23	(257/e23.\$4).cds. and \$5repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L462	1	(257/e23.\$4).cds. and anti near2 repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26

L463	1	("257"/\$6).cds. and anti near2 repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L464	0	("257"/\$6).cds. and solder near2 (resist mask) with underfill with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L465	0	("257"/\$6).cds. and solder near2 (resist mask) with underfill\$3 with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L466	2	("257"/\$6).cds. and solder near2 (resist mask) with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L467	29	("257"/\$6).cds. and solder near2 (resist mask) with (improv\$3, increas\$3) with attach \$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L468	4	("5703402"   "5801440"   "6329228").PN. OR ("6608388").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L469	20	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L470	24	("2671844"   "3488840"   "4661192"   "4706811"   "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L471	2	"3488840".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26

L472	12	("4604644"   "5084961"   "5089440"   "5121190"   "5194930"   "5274913"   "5400950"   "5542601"   "5578525"   "5615477"   "5704116"   "5710071").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L473	129	("5710071").URPN.	USPAT	OR	ON	2008/08/18 09:26
L474	5	"5,71,071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L475	2	"5710071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L476	2	"5,710,071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L477	11	("4604644"   "5144747"   "5182632"   "5203076"   "5218234"   "5296738"   "5311059"   "5385869"   "5473512"   "5488200"   "5594626").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L478	115	("4138691"   "4268848"   "4280132"   "4843036"   "5001542"   "5107325").PN. OR ("5218234").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L479	3455	257/778.cds.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L480	686	L479 and solder near2 (resist mask )	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L481	374	L480 and polyimide	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L482	260	L480 and polyimide	USPAT	OR	ON	2008/08/18 09:26

L483	29	("4658332"   "4740414"   "4847136"   "4847146"   "4855872"   "4873615"   "5026624"   "5110867"   "5258648"   "5262280"   "5278010"   "5304457"   "5329423"   "5391435"   "5439766"   "5439779"   "5473119"   "5493075"   "5496769"   "5511306"   "5535101"   "5579573"   "5633535"   "5801446"   "5808874"   "5821305"   "5866952"   "6002590"   "6054250").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L484	158	("4604644"   "4864470"   "4931345"   "5107325"   "5172303"   "5241133"   "5378869").PN. OR ("5535101").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L485	1876934	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L486	113324	L485 and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L487	67123	L485 and "438"/\$.ccls.	USPAT	OR	ON	2008/08/18 09:26
L488	37101	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L489	2357	L488 and "438"/\$.ccls.	USPAT	OR	ON	2008/08/18 09:26
L490	21999	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers	USPAT	OR	ON	2008/08/18 09:26

L491	354333	L490 and solder ball	USPAT	OR	ON	2008/08/18 09:26
L492	316	L490 and solder near2 ball	USPAT	OR	ON	2008/08/18 09:26
L493	14	polyimide near2 substrate with thickness with micrometers	USPAT	OR	ON	2008/08/18 09:26
L494	41	polyimide near5 substrate with thickness with micrometers	USPAT	OR	ON	2008/08/18 09:26
L495	27	L494 not L493	USPAT	OR	ON	2008/08/18 09:26
L496	7	("3948429"   "4255644"   "4300715"   "4371912"   "4607779"   "4638937"   "4638938").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L497	39	("3948429"   "4255644"   "4300715"   "4371912"   "4607779"   "4638937"   "4638938").PN. OR ("5201451").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L498	1062	thin with polyimide with substrate and "257"/\$. ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L499	659	thin with polyimide with substrate and "257"/\$. ccls.	USPAT	OR	ON	2008/08/18 09:26
L500	54	thin with polyimide with substrate with "mu.m" and "257"/\$.ccls.	USPAT	OR	ON	2008/08/18 09:26
L501	236	(IC integrated near1 circuit chip die semiconductor silicon wafer) and thin with polyimide with substrate with "mu.m"	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L502	134	L501 not "44"	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L503	184	L501 not L500	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L504	79	L501 not L500	USPAT; USOCR	OR	ON	2008/08/18 09:26
L505	419	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m"	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26



L506	239	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m"	USPAT	OR	ON	2008/08/18 09:26
L507	0	jp-361633-\$.did.	USPAT	OR	ON	2008/08/18 09:26
L508	0	jp-361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L509	1	jp-1361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L510	0	jp-11361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L511	2	JP-2001176918-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L512	20	("20010002066"   "20010040290"   "20010054751"   "4263606"   "4676864"   "4786545"   "4963974"   "5049718"   "5060052"   "5132772"   "5139610"   "5384204"   "5844304"   "5910685"   "6028011"   "6175151"   "6262488"   "6297142").PN. OR ("6518649").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L513	18	("20010002066"   "20010040290"   "20010054751"   "4263606"   "4676864"   "4786545"   "4963974"   "5049718"   "5060052"   "5132772"   "5139610"   "5384204"   "5844304"   "5910685"   "6028011"   "6175151"   "6262488"   "6297142").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26

L514	1	("6592783").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L515	17	("4551912"   "4811081"   "4851964"   "4977441"   "5032542"   "5075252"   "5153707"   "5232532"   "5427641"   "5726491"   "5949134"   "6100112"   "6274405"   "6313526"   "6315156"   "6388888"   "6559524").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L516	7	("5260168"   "5378581"   "5825081"   "6313526"   "6320135"   "6388888"   "6433414").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L517	18	("20010002066"   "20010040290"   "20010054751"   "4263606"   "4676864"   "4786545"   "4963974"   "5049718"   "5060052"   "5132772"   "5139610"   "5384204"   "5844304"   "5910685"   "6028011"   "6175151"   "6262488"   "6297142").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/18 09:26
L518	2	jp-2001176918-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L519	2	"20020043713".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L520	1073	(257/797).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 09:26
L521	7	L520 and dummy near2 pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26

L522	15	L520 and mark with probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 09:26
L523	780	(257/684).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 10:04
L524	1473	(257/701).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 10:04
L525	965	(257/782).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/18 10:04
L526	3135	I523 I524 I525	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 10:05
L527	0	I526 and antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 10:05
L528	0	I526 and antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/18 10:06
L529	101	((bump solder projection electrode ball) and (semiconductor chip die IC integrated adj circuit wafer silicon micro \$3device) and ( anti \$repellent repellent)). dm.	US-PGPUB	OR	ON	2008/08/18 10:09

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